

## Week 6 Student Checklist

- Review the overall Process Flow.

This can be found in bcourse: Files —> Lab Materials —> Overall Fabrication Process Flow [Current Semester].pdf

- Read the detailed Process Flow for week 6

Week 6: Contact Cut. Please read through the process step in detail and you should understand how to ensure complete opening of the contact holes, without causing shorts to the gate layer. NOTE: WE ARE ALMOST THERE! The devices have now been made. We need to make the metal contacts to them so that we can make measurements. This lab is very critical in the sense that if the contact hole is not completely opened and if the oxide is not completely removed, then all you have done till now cannot be “electrically accessible” and therefore, can get wasted.

- It is a usual lithography step, but the alignment is the hardest of all the lithography steps we have done till now. Go through the mask layout and think about what to expect. Note: It is a dark field mask and seeing the wafer below is difficult.
- Go through the Quintel Mask Aligner Manual. Review the Vernier Tutorial to measure your misalignment.

The manuals are available in bcourse: Files —> Lab Materials —> “Lab References”